A liquid applying system according to the present invention comprises a liquid supply source and a nozzle communicating with the liquid supply source. The nozzle comprises a liquid storing portion for storing a liquid supplied from the liquid supply source, a number of small passages communicating with the liquid storing portion, each of the small passages having a transverse section which is smaller than that of the liquid storing portion, and a slit-like passage communicating with the small passages, in which liquids from the small passages flow together and from which the liquids are continuously discharged like a curtain toward a semiconductor wafer.